

ISO-Cream® No-clean SMD solder pastes

Homogeneous, ready-to-use, low-odor mixture of metal powder, binding agents, solvents, fluxing agents, and thixotropic agents. 250 g and 500 g cans, 5, 10, and 30 cc dispenser cartridges

“Active-Clear“

Excellent wetting on all PCB surfaces, especially NiAu and NiPd under normal, inert gas atmosphere and in the vapor phase, based on synthetic resins (rosin-free), clear inconspicuous residues, minimal void formation, halide content < 0.15% (REL1)

“Clear“

Halide-free version of our ISO-Cream® “Active-Clear“, based on synthetic resins (rosin-free), clear inconspicuous residues, minimal void formation, processing period at least 72 hours, halide-free (<0.01%), RELO

“Clear“ GreenTin®

Halide-free version of our ISO-Cream® “Active-Clear“, Based on synthetic resins (colophony-free), clear inconspicuous residues, minimal void formation, processing period at least 72 hours, halide-free (<0.01%), RELO



Significant reduction in CO2 footprint

With **GreenTin**, we have opted for sustainable and high-purity tin from the refinery, which is obtained entirely from recycled materials. Through precise upcycling processes, the refinery achieves purity levels of up to 99.99%. The result is an ecologically sourced material of the highest quality. Instead of raw materials from mines, we rely on a particularly environmentally friendly European alternative.

Alloy	CO ₂ -Emission (per kg)			
	Primary metal*	Proportionately	Recycling metal	Proportionately
Sn96.5Ag3Cu0.5				
96.5 % Zinn	10.15 kg	9.795 kg	0.93 kg	0.897 kg
3.0 % Silber	449.39 kg	13.48 kg	52.0 kg	1.560 kg
0.5 % Kupfer	4.87 kg	0.024 kg	0.8 kg	0.004 kg
CO ₂ - Footprint		23.305 kg		2.461 kg
CO2 reduction of 20,844 kg = 89.44 %! comparison of the solder powder content of an SMD solder paste made from primary metals				

Lead-free alloys	Melting range
Sn96.5Ag3Cu0.5	217 - 219 °C
Sn100Ni+® / SN100-403C®	227 °C eutectic
Sn99.25Cu0.7Ni0.05	
Sn95.5Ag3.8Cu0.7	217 °C eutectic
Sn96.5Ag3.5	221 °C eutectic
Sn77.2In20Ag2.8	175 - 187 °C

Lead-free alloys	Melting range
Sn62Pb36Ag2	179 °C eutectic
Pb93Sn5Ag2	296 - 301 °C

Other alloys available on request.

Grain sizes		
Typ 2	Standard	45 - 75 µm
Typ 3	Fine-Pitch	25 - 45 µm
Typ 4	Fine-Pitch	20 - 38 µm
Typ 5	Ultra-Fine-Pitch	15 - 25 µm
Typen 6-8	Upon request	

* Efficiency Agency NRW

Property	ISO-Cream Clear	ISO-Cream Clear  GreenTin®	ISO-Cream Active-Clear	ISO-Cream EL 42/58	ISO-Cream EWL 2303	ISO-Cream RA 2601
EN ISO 9454-1 / 61190-1-1	1231 / RELO	1231 / RELO	1222 / REL1	1122 / ROL1	2131 / ORM0	1123 / ROM1
No Clean	•	•	•	•		
Residues easily removable	•	•	•	•	•	•
Stencil printing	•	•	•	•	•	•
Dispenser	•	•	•	•	•	
Jetprint	•	•	•		•	
Stamp printing / Pin in paste	•	•	•		•	
Vapor phase	•	•	•			
Stickiness > 48 Std.	•	•	•			
Unleaded	•	•	•	•	•	•
Containing lead					•	•
High lead content (Pb > 85 %)	•	•	•			•

SMD special soft solder paste

Homogeneous, ready-to-use, low-odor mixture of metal powder, binders, solvents, fluxing agents, and thixotropic agents.

- ISO-Cream® “RA 2601”** Flux according to DIN EN ISO 9454-1, 1123, or DIN EN 61190-1-1, ROM1. Especially for soldering partners with poor wettability. The flux residues on the soldered circuits should be removed.
- ISO-Cream® “EL 42/58”** No-clean SMD solder paste for temperature-sensitive components such as LEDs, low peak temperature (approx. 170 °C) in the soldering process, solderable under normal and protective gas atmospheres, high contour stability, halide content < 0.15% (ROL1)
- ISO-Cream® “EL 42/57/1”** Alloy: Bi58Sn42 - 138 °C eutectic
Alloy: Bi57Sn42Ag1 - 138 -139 °C
- ISO-Cream® “EWL 2303”** Water-soluble solder paste for excellent wetting on all known surfaces. Flux, ISO 9454-1:2016, 2131, DIN EN 61190-1-3/ IPC J-STD-004B, ORM0



Description	Contents
Cans	0.250 and 0.500 kg
Cartridges	6 and 12 oz
Dispenser cartridges	5, 10 and 30 ccm
Other containers are available on request.	



Made in Germany